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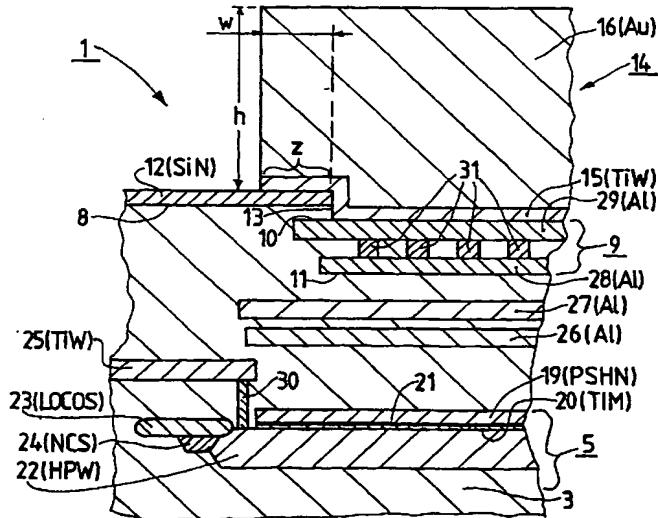
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(54) Title: INTEGRATED CIRCUIT WITH AT LEAST ONE BUMP



(57) Abstract: In an integrated circuit (1) having a substrate (3) and having a signal-processing circuit (4) which is produced at a surface (8) of the substrate (3), there is provided on the substrate surface (8) a protective layer (12) that has at least one aperture (13) through which a second contact pad (14) is electrically and mechanically connected to a first contact pad (9), wherein the second contact pad (14) is of a height of at least 15 μm and projects laterally beyond the aperture (13) on all sides and is seated on the protective layer (12) by an overlap zone (z) that is closed on itself like a ring, wherein the overlap zone (z) has a constant width of overlap (w) of between 2 μm and 15 μm , and wherein at least one element of the signal-processing circuit (4), and preferably only one capacitor (5) of the signal-processing circuit (4), is provided opposite the first contact pad (9).